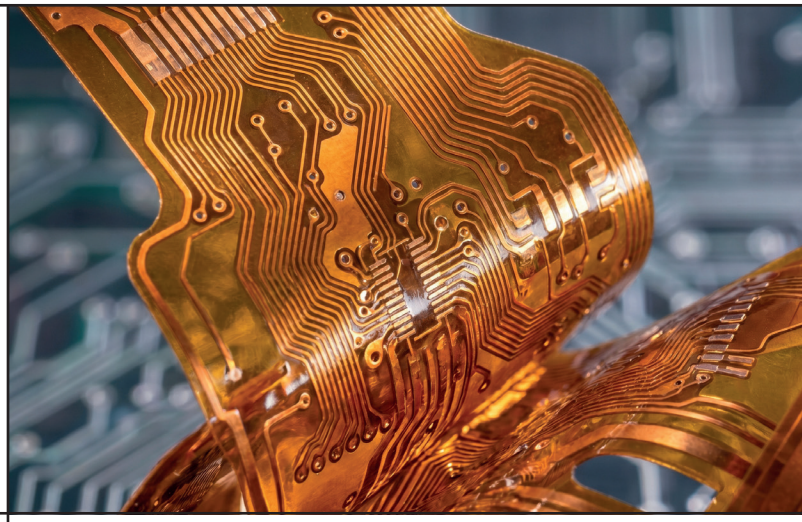
ZENIMID™
POLYIMIDES

ZENIMID™ POLYIMIDES FOR ADVANCED ELECTRONICS APPLICATIONS

Expanding the possibilities of next-generation electronics through ultra-high-performance polymer technology

WHAT ZENIMID™ POLYIMIDES ENABLE ?

- → **ULTRA-THIN FILM CAPABILITY**
- → **HIGH THERMAL STABILITY**
- → **ELECTRICAL INSULATION PERFORMANCE**
- → **DIMENSIONAL STABILITY**
- → **HIGH FLEXIBILITY**
- → **SUPPORT FOR HIGH-DENSITY INTEGRATION**



WHERE ZENIMID™ POLYIMIDES ARE USED

- → **Flexible printed circuits (FPCBs)**
- → **Semiconductor processing environments**
- → **Thermal management graphite sheets**
- → **High-density electronic systems**
- → **Foldable and compact electronic devices**

WHY ZENIMID™ POLYIMIDES PERFORM ?

- → **Enable compact and miniaturized electronic architectures**
- → **Support reliable operation in high-density electronic assemblies**
- → **Maintain stable performance under thermal and mechanical stress**
- → **Ensure long-term reliability of sensitive electronic components**
- → **Enable integration of flexible and ultra-thin circuit technologies**
- → **Contribute to robust electronic system design in demanding environments**

HPP – n° 06.2026 – Design : JG, Images: Adobe Stock

DESIGNED FOR ADVANCED ELECTRONICS ENVIRONMENTS

Zenimid™ Polyimide films are engineered for advanced electronics applications requiring reliable electrical, thermal, and mechanical performance in compact and high-performance systems.

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